



New Products
October 2018



# Symbols

### **Mating configuration**



Parallel



Perpendicular



Horizontal



Direct Connector



Cable

### **Termination**



SMT



Press-fit



Through-Hole



THTR

### **Application**



Power



High Speed



High Density



Rugged



FIVIC

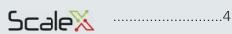


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### Zero8

0.8 mm SMT for Board-to-Board





### **EC.8**

0.8 mm SMT - Edge Card Connector



.....16

### **Customer Specific Connectors**

Individually developed and produced







### Zero8 - 0.8 mm SMT for Board-to-Board Applications

#### Scalable & Robust

The product group Zero8 with ScaleX technology offers a high level of design, stacking and pin count scalability. This connector series is available with double sided shielding. The shielding can be omitted in future variations.

The robust ScaleX connector technology ensures a secure contact during mechanical stress (vibration, shock) and compensates for unit tolerances in all directions (x,y,z). The connector's sophisticated geometry protects its contacts from faulty handling.



ScaleX - Double sided, robust contact technology in a versatile and scalable connector system.

For more information please visit www.ept.de/Zero8

#### **Key Features:**

- up to 16 Gbps
- 12 to 80 pins
- 1.4 A operational current
- 500 mating cycles
- reliable contact
- optimized contact damage prevention
- packed in Tape & Reel

#### **Applications:**

- board-to-board (mezzanine) from 6 - 20 mm
- parallel and perpendicular connection
- optional: unshielded version

#### Termination



SMT

#### **Application**



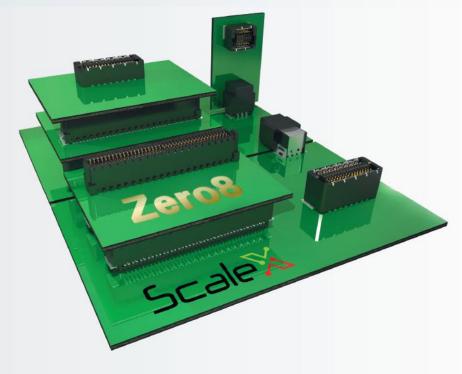
High Density



High Speed



EMC







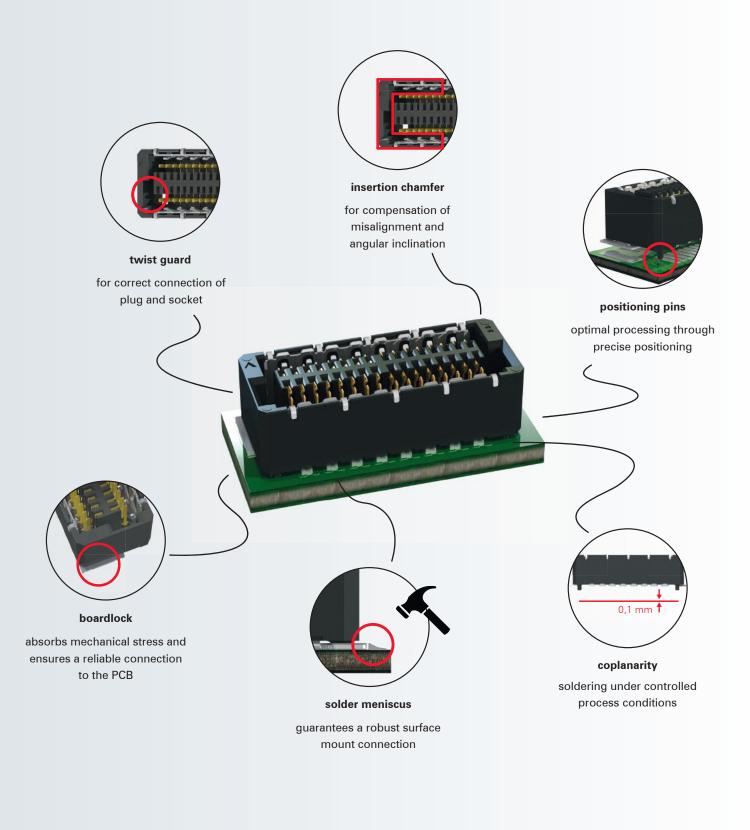
### Zero8 - Product Overview

				Ma	ting configurat	ion	
Type of Zero8 o	connector	Height	Number of pins	Parallel	Horizontal	Perpendicular	Page
Employed,	Socket low-profile	4.85 mm	12 80	<b>✓</b>		<b>✓</b>	Coming soon
	Socket mid-profile	7.85 mm	12 80	<b>✓</b>		✓	12
	Plug low-profile	1.15 mm	12 80	✓		<b>✓</b>	Coming soon
	Plug mid-profile	2.65 mm	12 80	<b>✓</b>		<b>√</b>	14
	Socket angled		12 80		✓	<b>✓</b>	Coming soon
	Plug angled		12 80		✓	<b>✓</b>	Coming soon





### Advantages of the Zero8 Connector









double sided contact system

double sided contact system
for a secure connection in the
industrial environment
(shock, vibration, thermal cycles,
corrosive gas)



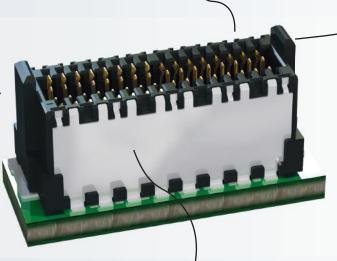
#### smooth contact surface

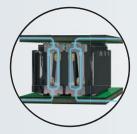
smooth surface: the contact on the homogenous rolled side with high-end surface allows for up to 500 mating cycles



protected contacts

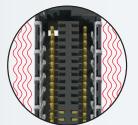
optimized contact and casing geometry reduce damage to contacts





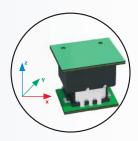
data flow

HF optimized contact geometry ensures data transfer speeds of up to 16 Gpbs



**EMC** shielding

double sided shielding ensures a high electromagnetic compatibility for optimal signal integrity in the industrial environment



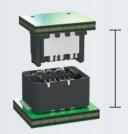
tolerance compensation

high reliability through tolerance compensation





### PCB Distances Board-to-Board

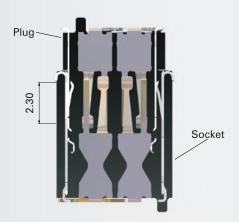


6.00 - 20.00 mm

Board-to-Board distances of 6.00 to 20.00 mm can be achieved using Zero8 connections.

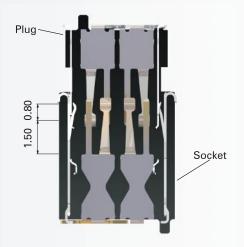
		THE LA			Hat.
PCB distance (min max.)	6.00 - 7.50 mm	7.50 - 9.00 mm	9.00 - 10.50 mm	10.50 - 12.00 mm	12.00 - 20.00 mm
Socket height	low-profile 4.85 mm (coming soon)	low-profile 4.85 mm (coming soon)	mid-profile 7.85 mm (see page 12)	mid-profile 7.85 mm (see page 12)	high-profile (coming soon)
Plug height	low-profile 1.15 mm (coming soon)	mid-profile 2.65 mm (see page 14)	low-profile 1.15 mm (coming soon)	mid-profile 2.65 mm (see page 14)	high-profile (coming soon)

## Connection for min. PCB distance



The minimum possible board-to-board distance is achieved by plugging the connector all the way in to the stop position.

## Connection for max. PCB distance



The plug and socket can be inserted anywhere within a range of 1.5 mm, thus allowing for the maximum possible board-to-board distance. The remaining 0.8 mm ensure secure contact mating.

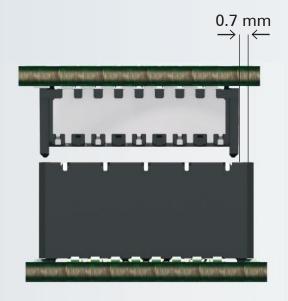




## Misalignment Zero8 Connectors

Allowed misalignment tolerances

longitudinal: ± 0.7 mm



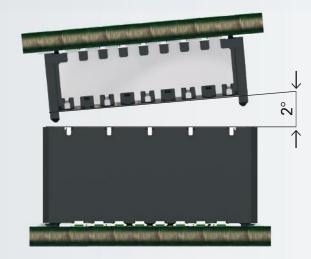
transverse:  $\pm$  0.7 mm

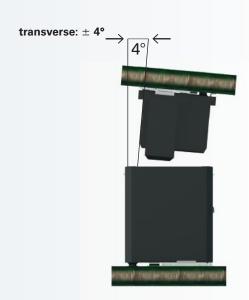


### Angular Inclination Zero8 Connectors

#### Allowed angular inclination tolerances

longitudinal: ± 2°





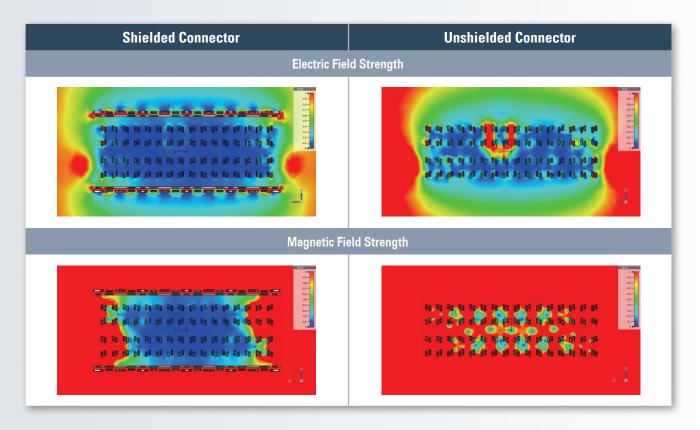




## Electromagentic Compatibility

The double sided shielding concept guarantees a interference-free HighSpeed transfer for the industrial environment: The utilized shielding material works especially well for components with high electromagentic compatibility requirements and guarantees a coupling inductivity of max. 10pH for the connector.

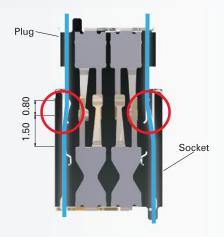
Electric and magnetic field strength influence of the connector can be simulated through the coupling inductivity.



The extensive shielding concept uses multiple contact points to channel interferences away from mass connections.

Secure connections of individual PCB distances of 6 - 20 mm are guaranteed by the shielding concept's extended mating area of 2.3 mm.

The shielding concept not only protects the connector from electromagentic influences but also the neighboring components, should the connector be a source of interference.

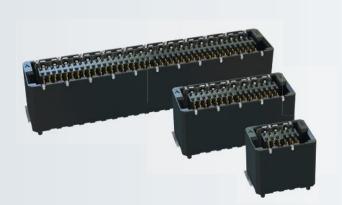




## **Technical Specifications**

Test Standard         U.8 mim SMT Board-to-Board Connectors           Basics         12/20/32/52/80           Number of pins         12/20/32/52/80           Grammation         SMT           Operating temperature range         -55°C bis +125°C           Material         LCP           CTI value         IEC 60112         150           Contact material         Copper alloy           Contact surface         Au over Ni           Termination area         Sn over Ni           Mechanical	Toological anguification		Zero8
Number of pins   12 / 20 / 32 / 52 / 80	Technical specification	Test Standard	0.8 mm SMT Board-to-Board Connectors
Termination   SMT   Operating temperature range   -55°C bis +125°C	Basics		
Operating temperature range	Number of pins		12 / 20 / 32 / 52 / 80
Material         Insulator material         LCP           CTI value         IEC 60112         150           Contact material         Copper alloy           Contact surface         Au over Ni           Termination area         Sn over Ni           Mechanical         Pitch         0.8 mm           Mating- and separating force per Contact shielded / unshielded         ≤1.2 N / ≤ 0.6 N           Coplararity         Performance level I: 500 mating cycles           Coplararity         max. 0.1 mm           Vibration, sinusoidal         IEC 60512-9-1:2010         Performance level I: 500 mating cycles           Contact mating problems if vibrations occur, sinusoidal         IEC 60512-6-4:2002         10 - 2000 Hz           Contact mating problems if shocks occur, semi-sinusoidal         IEC 60512-6-3:2002         50 g         11 ms           Contact mating problems if shocks occur, semi-sinusoidal         IEC 60512-5-2:2003         < 1 μs	Termination		SMT
Insulator material   LCP	Operating temperature range		-55°C bis +125°C
CTI value   IEC 60112   150   Copper alloy	Material		
Contact surface         Copper alloy           Contact surface         Au over Ni           Termination area         Sn over Ni           Mechanical         Pitch         0.8 mm           Mating- and separating force per Contact shielded / unshielded         ≤ 1.2 N / ≤ 0.6 N           Coplanarity         Performance level I: 500 mating cycles           Coplanarity         max. 0.1 mm           Vibration, sinusoidal         IEC 60512-6-4:2002         10 - 2000 Hz 20 g           Contact mating problems if vibrations occur, sinusoidal         IEC 60512-6-3:2002         < 1 μs	Insulator material		LCP
Contact surface   Au over Ni	CTI value	IEC 60112	150
Termination area       Sn over Ni         Mechanical       Pitch       0.8 mm         Mating- and separating force per Contact shielded / unshielded       ≤ 1.2 N / ≤ 0.6 N         Durability       IEC 60512-9-1:2010       Performance level I: 500 mating cycles         Coplanarity       max. 0.1 mm         Vibration, sinusoidal       IEC 60512-6-4:2002       10 - 2000 Hz         Contact mating problems if vibrations occur, sinusoidal       IEC 60512-2-5:2003       < 1 μs         Contact mating problems if shocks occur, semi-sinusoidal       IEC 60512-6-3:2002       11 ms         Contact mating problems if shocks occur, semi-sinusoidal       IEC 60512-2-5:2003       < 1 μs         Electrical       IEC 60512-2-2-2:2002       max. 1.4 A at 20°C (52 pins)         Contact resistance       IEC 60512-3-1:2002       max. 25 mΩ         Clearance and creepage       IEC 60512-3-1:2002       min. 5 Ω         Test voltage       IEC 60512-3-1:2002       min. 5 Ω         Data transfer speed       16 Gbps <t< td=""><td>Contact material</td><td></td><td>Copper alloy</td></t<>	Contact material		Copper alloy
Mechanical       Pitch       0.8 mm         Mating- and separating force per Contact shielded / unshielded $\leq 1.2 \text{ N}/\leq 0.6 \text{ N}$ Durability       IEC 60512-9-1:2010       Performance level 1: 500 mating cycles         Coplanarity       max. 0.1 mm         Vibration, sinusoidal       IEC 60512-6-4:2002       10 - 2000 Hz 20 g         Contact mating problems if vibrations occur, sinusoidal       IEC 60512-2-5:2003 $< 1  \mu s$ Shock, semi-sinusoidal       IEC 60512-6-3:2002       50 g 11 ms         Contact mating problems if shocks occur, semi-sinusoidal       IEC 60512-2-5:2003 $< 1  \mu s$ Electrical       IEC 60512-2-5:2002       max. 1.4 A at 20°C (52 pins)         Contact resistance       IEC 60512-2-1:2002       max. 25 mΩ         Clearance and creepage       min. 0.25 mm         Insulation resistance       IEC 60512-3-1:2002       min. 5 $\Omega$ Test voltage       IEC 60512-4-1:2003       500 V AC         Data transfer speed       16 Gbps         Coupling inductivity       10 pH         Processing       max. SMT reflow soldering temperature 20 - 40 s at 260         MSL       JEDEC J-STD-020E       max. SMT reflow soldering temperature 20 - 40 s at 260         Approval       Pick and place	Contact surface		Au over Ni
Pitch  Mating- and separating force per Contact shielded / unshielded  Durability  Coplanarity  Coplanarity  Vibration, sinusoidal  Contact mating problems if vibrations occur, sinusoidal  Shock, semi-sinusoidal  Contact mating problems if shocks occur, semi-sinusoidal  Operational current  Clearance and creepage  Insulation resistance  Test voltage  Coupling inductivity  Processing  Soldering temperature  MSL  Packaging  Approval  Durability  IEC 60512-9-1:2010  Performance level I: 500 mating cycles  Performance level III mating  Perfor	Termination area		Sn over Ni
Mating- and separating force per Contact shielded / unshielded       ≤ 1.2 N / ≤ 0.6 N         Durability       IEC 60512-9-1:2010       Performance level I: 500 mating cycles         Coplanarity       max. 0.1 mm         Vibration, sinusoidal       IEC 60512-6-4:2002       10 - 2000 Hz 20 g         Contact mating problems if vibrations occur, sinusoidal       IEC 60512-2-5:2003       < 1 μs         Shock, semi-sinusoidal       IEC 60512-6-3:2002       50 g 11 ms         Contact mating problems if shocks occur, semi-sinusoidal       IEC 60512-2-5:2003       < 1 μs         Electrical         Operational current       IEC 60512-2-5:2002       max. 1.4 A at 20°C (52 pins)         Contact resistance       IEC 60512-2-1:2002       max. 25 mΩ         Clearance and creepage       min. 5 GΩ         Insulation resistance       IEC 60512-3-1:2002       min. 5 GΩ         Data transfer speed       16 Gbps         Coupling inductivity       10 pH         Processing         Soldering temperature       JEDEC J-STD-020E       max. SMT reflow soldering temperature 20 - 40 s at 260         MSL       JEDEC J-STD-020E       max. SMT reflow soldering temperature 20 - 40 s at 260         Approval       Approval	Mechanical		
Contact shielded / unshielded  Durability  EC 60512-9-1:2010  Performance level I: 500 mating cycles  max. 0.1 mm  Vibration, sinusoidal  Contact mating problems if vibrations occur, sinusoidal  Shock, semi-sinusoidal  EC 60512-6-3:2002  Contact mating problems if shocks occur, semi-sinusoidal  EC 60512-2-5:2003  Contact mating problems if shocks occur, semi-sinusoidal  EC 60512-2-5:2003  Contact mating problems if shocks occur, semi-sinusoidal  EC 60512-2-5:2003  Contact mating problems if shocks occur, semi-sinusoidal  EC 60512-2-5:2003  Contact mating problems if shocks occur, semi-sinusoidal  EC 60512-2-5:2003  Contact mating problems if shocks occur, semi-sinusoidal  EC 60512-2-5:2003  Contact mating problems if shocks occur, semi-sinusoidal  EC 60512-2-1:2002  max. 1.4 A at 20°C (52 pins)  Tec 60512-2-1:2002  max. 25 mΩ  Clearance and creepage  min. 0.25 mm  Insulation resistance  IEC 60512-3-1:2002  min. 5 GΩ  Test voltage  IEC 60512-3-1:2003  Test voltage  Test voltage  Coupling inductivity  To pH  Processing  Soldering temperature  JEDEC J-STD-020E  max. SMT reflow soldering temperature 20 - 40 s at 260  MSL JEDEC J-STD-020E  Tape and Reel  Assembly  Pick and place	Pitch		0.8 mm
Coplanarity Vibration, sinusoidal Vibration, sinusoidal Vibration, sinusoidal Contact mating problems if vibrations occur, sinusoidal Shock, semi-sinusoidal Contact mating problems if shocks occur, semi-sinusoidal Contact mating problems if shocks occur, semi-sinusoidal Contact mating problems if shocks occur, semi-sinusoidal Electrical  Operational current Contact resistance IEC 60512-2-5:2002  Max. 1.4 A at 20°C (52 pins)  Contact resistance IEC 60512-2-1:2002  Max. 25 mΩ  Clearance and creepage Insulation resistance IEC 60512-3-1:2002  Min. 0.25 mm Insulation resistance IEC 60512-3-1:2002  Min. 5 GΩ  Test voltage IEC 60512-4-1:2003  Data transfer speed Coupling inductivity  Processing  Soldering temperature JEDEC J-STD-020E  MSL JEDEC J-STD-020E  MSL Packaging Assembly Approval			$\leq$ 1.2 N / $\leq$ 0.6 N
Coplanarity Vibration, sinusoidal Vibration, sinusoidal Vibration, sinusoidal Contact mating problems if vibrations occur, sinusoidal Shock, semi-sinusoidal Contact mating problems if shocks occur, semi-sinusoidal Contact mating problems if vibrations in shocks occur, semi-sinusoidal Contact mating problems if vibrations in shocks occur, semi-sinusoidal Contact mating problems if vibrations in shocks occur, semi-sinusoidal Contact mating problems if vibrations in shocks occur, semi-sinusoidal Contact mating problems if vibrations in shocks occur, semi-sinusoidal Contact mating problems if vibrations in shocks occur, semi-sinusoidal Contact mating problems if vibrations occu	Durability	IEC 60512-9-1:2010	Performance level I: 500 mating cycles
Vibration, sinusoidal IEC 60512-6-4:2002 10 - 2000 Hz 20 g  Contact mating problems if vibrations occur, sinusoidal Shock, semi-sinusoidal IEC 60512-6-3:2002 50 g 11 ms  Contact mating problems if shocks occur, semi-sinusoidal IEC 60512-2-5:2003 < 1 μs  Electrical IEC 60512-2-5:2003	*		max. 0.1 mm
Shock, semi-sinusoidal IEC 60512-6-3:2002 50 g 11 ms  Contact mating problems if shocks occur, semi-sinusoidal IEC 60512-2-5:2003 <1 μs  Electrical		IEC 60512-6-4:2002	
Shock, semi-sinusoidal IEC 60512-0-3:2002 11 ms  Contact mating problems if shocks occur, semi-sinusoidal IEC 60512-2-5:2003		IEC 60512-2-5:2003	< 1 μs
Electrical   IEC 60512-2-3:2003   IEC 60512-5-2:2002   max. 1.4 A at 20°C (52 pins)	Shock, semi-sinusoidal	IEC 60512-6-3:2002	
Operational current       IEC 60512-5-2:2002       max. 1.4 A at 20°C (52 pins)         Contact resistance       IEC 60512-2-1:2002       max. 25 mΩ         Clearance and creepage       min. 0.25 mm         Insulation resistance       IEC 60512-3-1:2002       min. 5 GΩ         Test voltage       IEC 60512-4-1:2003       500 V AC         Data transfer speed       16 Gbps         Coupling inductivity       10 pH         Processing         Soldering temperature       JEDEC J-STD-020E       max. SMT reflow soldering temperature 20 - 40 s at 260         MSL       JEDEC J-STD-020E       1         Packaging       Tape and Reel         Assembly       Pick and place		IEC 60512-2-5:2003	< 1 μs
Contact resistance       IEC 60512-2-1:2002       max. 25 mΩ         Clearance and creepage       min. 0.25 mm         Insulation resistance       IEC 60512-3-1:2002       min. 5 GΩ         Test voltage       IEC 60512-4-1:2003       500 V AC         Data transfer speed       16 Gbps         Coupling inductivity       10 pH         Processing         Soldering temperature       JEDEC J-STD-020E       max. SMT reflow soldering temperature 20 - 40 s at 260         MSL       JEDEC J-STD-020E       1         Packaging       Tape and Reel         Assembly       Pick and place         Approval	Electrical		
Clearance and creepage       min. 0.25 mm         Insulation resistance       IEC 60512-3-1:2002       min. 5 GΩ         Test voltage       IEC 60512-4-1:2003       500 V AC         Data transfer speed       16 Gbps         Coupling inductivity       10 pH         Processing         Soldering temperature       JEDEC J-STD-020E       max. SMT reflow soldering temperature 20 - 40 s at 260         MSL       JEDEC J-STD-020E       1         Packaging       Tape and Reel         Assembly       Pick and place	Operational current	IEC 60512-5-2:2002	max. 1.4 A at 20°C (52 pins)
Insulation resistance IEC 60512-3-1:2002 min. 5 GΩ  Test voltage IEC 60512-4-1:2003 500 V AC  Data transfer speed 16 Gbps  Coupling inductivity 10 pH  Processing  Soldering temperature JEDEC J-STD-020E max. SMT reflow soldering temperature 20 - 40 s at 260  MSL JEDEC J-STD-020E 1  Packaging Tape and Reel  Assembly Pick and place	Contact resistance	IEC 60512-2-1:2002	max. 25 mΩ
Insulation resistance IEC 60512-3-1:2002 min. 5 GΩ  Test voltage IEC 60512-4-1:2003 500 V AC  Data transfer speed 16 Gbps  Coupling inductivity 10 pH  Processing  Soldering temperature JEDEC J-STD-020E max. SMT reflow soldering temperature 20 - 40 s at 260  MSL JEDEC J-STD-020E 1  Packaging Tape and Reel  Assembly Pick and place	Clearance and creepage		min. 0.25 mm
Test voltage IEC 60512-4-1:2003 500 V AC  Data transfer speed 16 Gbps  Coupling inductivity 10 pH  Processing  Soldering temperature JEDEC J-STD-020E max. SMT reflow soldering temperature 20 - 40 s at 260  MSL JEDEC J-STD-020E 1  Packaging Tape and Reel  Assembly Pick and place  Approval		IEC 60512-3-1:2002	
Data transfer speed Coupling inductivity 10 pH  Processing  Soldering temperature JEDEC J-STD-020E max. SMT reflow soldering temperature 20 - 40 s at 260 MSL JEDEC J-STD-020E 1 Packaging Tape and Reel Assembly Pick and place  Approval	Test voltage		
Coupling inductivity 10 pH  Processing  Soldering temperature JEDEC J-STD-020E max. SMT reflow soldering temperature 20 - 40 s at 260  MSL JEDEC J-STD-020E 1  Packaging Tape and Reel  Assembly Pick and place  Approval	-		
Processing  Soldering temperature JEDEC J-STD-020E max. SMT reflow soldering temperature 20 - 40 s at 260  MSL JEDEC J-STD-020E 1  Packaging Tape and Reel  Assembly Pick and place  Approval	·		·
Soldering temperature JEDEC J-STD-020E max. SMT reflow soldering temperature 20 - 40 s at 260  MSL JEDEC J-STD-020E 1  Packaging Tape and Reel  Assembly Pick and place  Approval	,		·
MSL JEDEC J-STD-020E 1 Packaging Tape and Reel Assembly Pick and place  Approval	-	JEDEC J-STD-020E	max. SMT reflow soldering temperature 20 - 40 s at 260°C
Packaging Tape and Reel Assembly Pick and place Approval			<u> </u>
Assembly Pick and place Approval			
Approval			•
	•		11
			F130314
Environment RoHS compliant			





Typ: Socket straight mid-profile

7.85 mm unmated

Number of pins: 12 to 80

Pitch: 0.8 mm

Operational current: 1.4 A bei 20°C (52 pins)

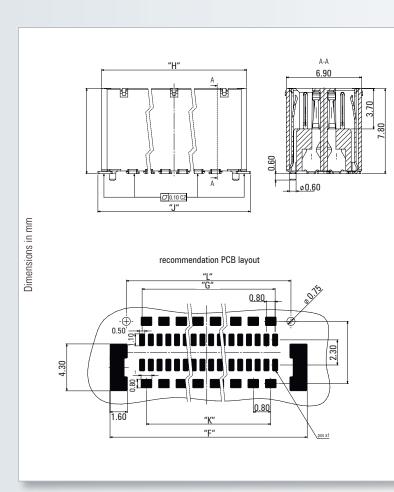
Packaging: Tape & Reel

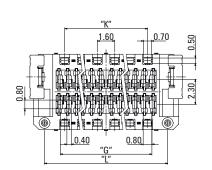
Approval: C SUS

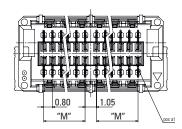
RoHS

Technial Specifications on page 11

For drawings and technical data visit www.ept.de







Pins	"F"	"G"	"H"	"J"	"K"	"Ľ"	"М"
12	9.88	4.00	8.90	9.58	3.20	6.90	1.60
20	13.08	7.20	12.10	12.78	6.40	10.10	3.20
32	17.88	12.00	16.90	17.58	11.20	14.90	5.60
52	25.88	20.00	24.90	25.58	19.20	22.90	9.60
80	37.08	31.20	36.10	36.78	30.40	34.10	15.20

Mating connector / Application:



for parallel applications (p. 14-15)







# Socket mid-profile - Performance level I

Number of pins	Part number	PU (Tape & Reel)
12	406-53112-51	
20	406-53120-51	
32	406-53132-51	250
52	406-53152-51	
80	406-53180-51	

### On request

- different number of pins
- other performance level







Typ: Plug straight mid-profile

2.65 mm unmated

Number of pins: 12 to 80

Pitch: 0.8 mm

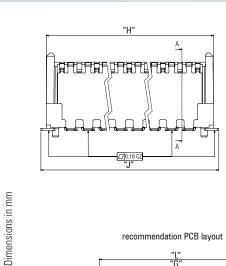
Operational current: 1.4 A at 20°C (52 pins)

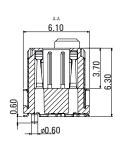
Packaging: Tape & Reel

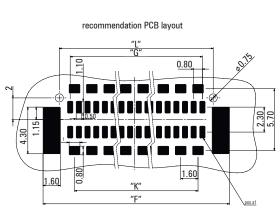
Approval: C SUS

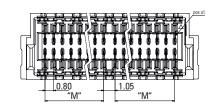
Technical Specifications on page 11

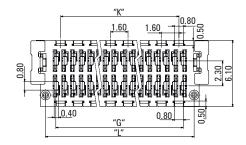
For drawings and technical data visit www.ept.de











Pins	"F"	"G"	"H"	"J"	"K"	"Ľ"	"М"
12	9.00	4.00	7.70	8.70	3.20	6.00	1.60
20	12.20	7.20	10.90	11.90	6.40	9.20	3.20
32	17.00	12.00	15.70	16.70	11.20	14.00	5.60
52	25.00	20.00	23.70	24.70	19.20	22.00	9.60
80	36.20	31.20	34.90	35.90	30.40	33.20	15.20

Mating connector / Application:



for parallel applications (p. 12-13)







## Plug mid-profile - Performance level I

Number of pins	Part number	PU (Tape & Reel)
12	405-53112-51	
20	405-53120-51	
32	405-53132-51	250
52	405-53152-51	
80	405-53180-51	

### On request

- different number of pins
- other performance level



### EC.8 – 0.8 mm SMT Edge Card Connector

#### Easy-to-use, HighSpeed, compact

ept expands its connector selection with a versatile 0.8 mm pitch solution. The EC.8 connector is built for speed: Compared to traditional connectors the EC.8 is made up of less components. This reduces changes in diameter and direction as well as reflections of the signal - the application receives quick, high integrity signals, at transfer speeds of up to 24 Gbps.

The edge card technology excels in the areas of data transfer and signal integrity. Well thought out features increase usability. Nothing stands in the way of its implementation into your HighSpeed applications.

For more information please visit www.ept.de/EC8

#### **Key Features:**

- Edge card connector
- 20 to 200 pins
- 24 Gbps transfer rate
- 3.2 A operational current
- 500 mating cycles
- packed in Tape & Reel, Tray
- 1.60 mm edge card thickness

#### Applications:

- embedded
- industrial automation
- datacom

#### **Termination**



SMT

#### **Application**



High Density



Perpendicular



Edge Card Connector

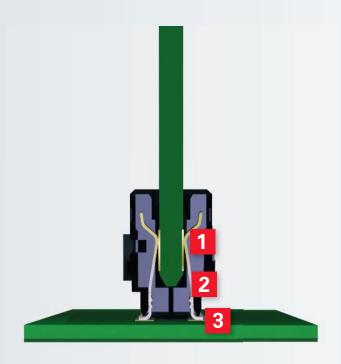




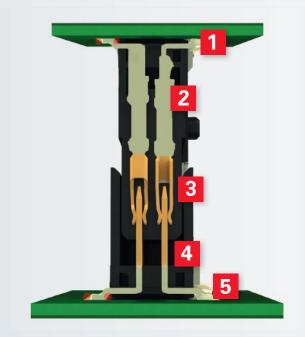


### EC.8 - Edge Card Connector vs. Connector Pair

The edge card connector enables a direct connection to the printed circuit board without the necessity of a connector mate. This results in fewer points of contact and junctions in comparison to a female-male connection setup. The operational current and transfer rate properties are therefore positively affected.



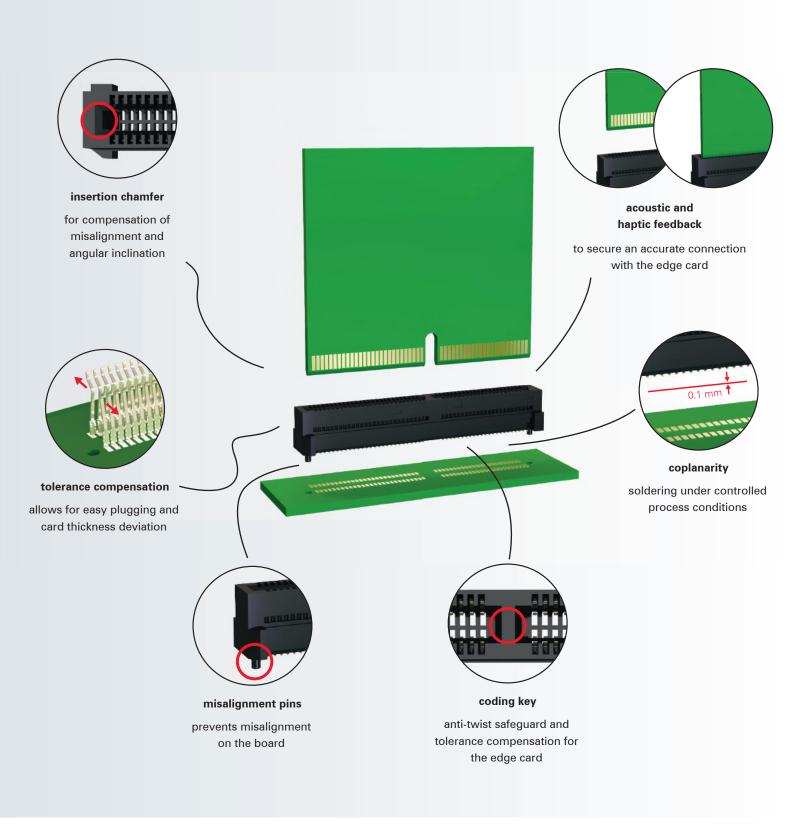
R Contact junction [1]
R Contact [2]
R PCB connection [3]



R PCB connection [1]
R Contact [2]
R Contact junction [3]
R Contact [4]
R PCB connection [5]



## Advantages of the EC.8 Edge Card Connector



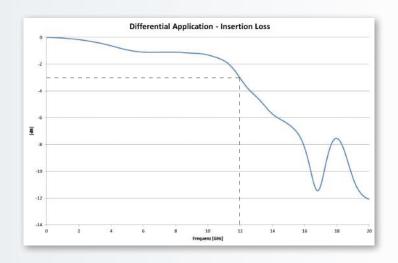
### HighSpeed - EC.8

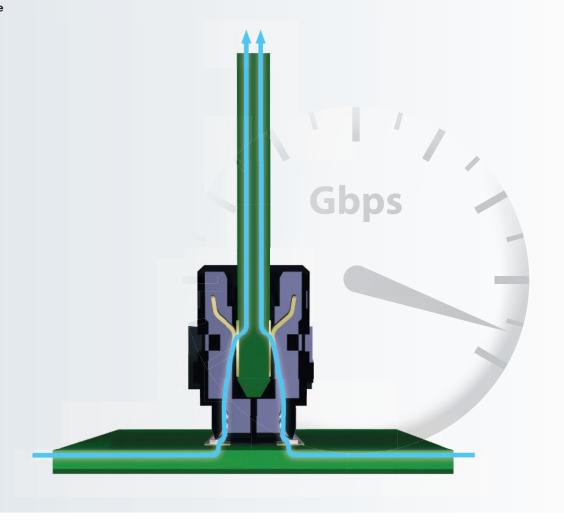
# The EC.8 edge card connector setup supports up to 24 Gbps!

Edge card connectors are present in many HighSpeed applications. The EC.8 connector is ready for a seamless integration as well. Since "HighSpeed" depends on much more than pure transfer rates many simulations have been carried out in ept development labs during which the signal integrity has been assessed based on a specific set of criteria.

A detailed report of the HighSpeed properties as well as the s-parameters of a simulation based on your own design are available upon request:

sales@ept.de



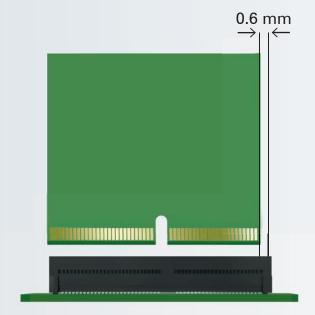


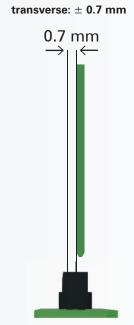


## Misalignment EC.8 Connectors

### Allowed misalignment tolerances

longitudinal: ± 0.6 mm

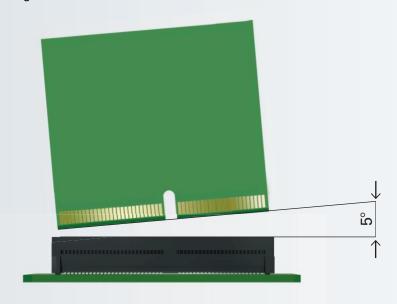


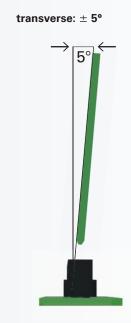


# Angular Inclination EC.8 Connectors

#### Allowed angular inclination tolerances

longitudinal: ± 5°





### **Technical Specifications**

		EC.8
Technical specifications	Test Standard	0.8 mm SMT Edge Card Connectors
Basics		
Number of pins		20 / 40 / 60 / 80 / 100 / 120 / 140 / 160 / 180 / 200
Termination		SMT
Operating temperature range		-55°C to +125°C
Material		
Insulator material		LCP
CTI value	IEC 60112	200
Contact material		Copper alloy
Contact surface		Au over PdNi over Ni
Termination area		Sn over Ni
Mechanical		
Pitch		0.8 mm
PCB thickness		1.60 mm
Mating force per pin		≤ 0.635 N
Seperating force per pin		≥ 0.06 N
Durability	IEC 60512-9-1:2010	Performance level I: 500 mating cycles
Coplanarity		≤ <b>0.1</b> mm
Vibration, sinusoidal	IEC 60512-6-4:2002	10 - 2000 Hz 20 g
Contact mating problems if vibrations occur, sinusoidal	IEC 60512-2-5:2003	≤1µs
Shock, semi-sinusoidal	IEC 60512-6-3:2002	50 g 11 ms
Contact mating problems if shocks occur, semi-sinusoidal	IEC 60512-2-5:2003	≤1μs
Electrical		
Operational current	IEC 60512-5-2:2002	3.2 A @ 20°C (8 of 140 pins) 1.35 A @ 20°C (140 pins)
Contact resistance	IEC 60512-2-1:2002	$\leq$ 15 m $\Omega$
Clearance and creepage		0.25 mm
Insulation resistance	IEC 60512-3-1:2002	≥1 <b>G</b> Ω
Test voltage	IEC 60512-4-1:2003	1100 V DC
Data transfer rate		24 Gbps
Processing		
Soldering temperature	JEDEC J-STD-020E	20 - 40 s at 260°C
MSL	JEDEC J-STD-020E	1
Packaging		Tape and Reel, Tray (starting at 160p)
Assembly		Pick and place
Approval		
UL file		E130314
Environment		RoHS compliant

### EC.8

### **Edge Card Connector (without key)**



Type: Edge card connector straight

7.8 mm height

Number of pins: 20 to 60

Pitch: 0.8 mm

Operational current: 3.2 A at 20°C (140 pins)

Packaging: Tape & Reel

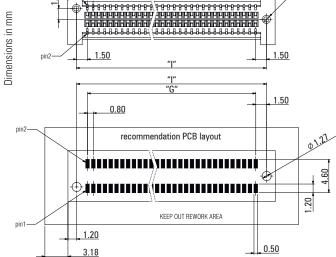
Approval:

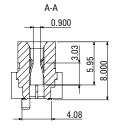
S SUS

RoHS COMPLIANT

Technical Specification on page 21

For drawings and technical data visit www.ept.de





Pins	"F" "G"		"I"
20	9.25	7.20	10.20
40	17.25	15.20	18.20
60	25.25	23.20	26.20

#### **More Options:**

for connectors with key (p. 24-25)

### **Edge Card Connector (without key)**



# Edge Card Connector - Performance Level I

Number of pins	Part number	PU (Tape & Reel)
20	408-52020-000-11	
40	408-52040-000-11	250
60	408-52060-000-11	



### **Edge Card Connector (with key)**



Type: Edge card connector straight

7.8 mm height

Number of pins: 60 to 200

Pitch: 0.8 mm

Operational current: 3.2 A at 20°C (140 pins)

Packaging: Tape & Reel, Tray

Approval:

0.55

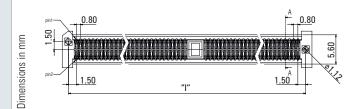
Rot COMPL

Technical Specification on page 21

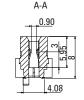
For drawings and technical data visit www.ept.de

min 1.413
max 1.727
nom 1.60
0.67

3.60



Ø 0.10 CZ



		recommenda	tion PCB layout			
			']"			
	-	"C."	G"			
	0.80	<u> </u>	1 1	-	1.50	
pin2					Į,	01.27
	<u> </u>		· - · - ·	//	*	4.60
pin1	1.20	<u> </u>	KEEP OUT REWORK AREA	0 <u>.50</u>		1.20
	3.18					

Pins	"C"	"F"	"G"	"l"
60	7.20	28.45	26.40	29.40
80	16.80	36.45	34.40	37.40
100	20.80	44.45	42.40	45.40
120	24.80	52.45	50.40	53.40
140	24.80	60.45	58.40	61.40
160	24.80	68.45	66.40	69.40
180	24.80	76.45	74.40	77.40
200	24.80	84.45	82.40	85.40

### **More Options:**

for connectors without key (p. 22-23)



# Edge Card Connector - Performance Level I

Number of pins	Part number	PU (Tape & Reel)
60	408-52060-100-11	
80	408-52080-100-11	
100	408-52100-100-11	250
120	408-52120-100-11	
140	408-52140-100-11	



# Edge Card Connector - Performance Level I

Number of pins	Part number	PU (Tray)
160	408-52160-100-12	90
180	408-52180-100-12	
200	408-52200-100-12	
	408-52200-103-12 (strengthened element along insulator)	

On Request

• Tape & Reel available

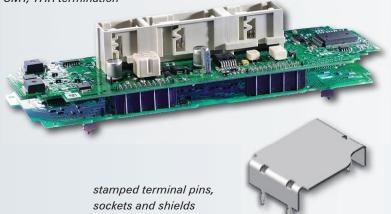


### **Customized Connectors**

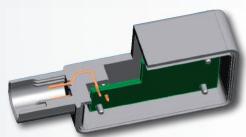
### Individually developed and produced



Male- & Female connectors in Press-fit, SMT, THR termination







overmolded & potted connectors

## "One Stop Supplier" for Customer Specific Connectors

#### **Precision meets Passion**

With its exceptional experienced employees, in-house tool-shop, and high vertical integration of manufacturing processes, ept is the perfect partner for customer specific connector solutions. Over the last 40 years, ept has proven to successfully develop and manufacture customized connectors in a variety of designs in different applications. ept's expertise is focused on stamped termination connectors, including examples of customized connector solutions such as shown above.

#### In-house from Your Request to SOP (Start of Production)

Starting with your request for a connection, ept's engineers are very experienced to develop a suitable, cost efficient and high quality product design. It is one of ept's major strengths to focus on a cost efficient design from the very beginning. In several projects we were able to reduce total cost of ownership up to 30% by adjusting the customers' original design for an optimized manufacturing process. Furthermore, cost efficiencies could be achieved by using already existing tools and equipment for customized applications.

ept's Project Managers follow a straight and targeted approach, based on the high requirements of APQP (Advanced Product Quality Planning) according to TS 16949. They make sure that deadlines are met, responses are given in short-notice, and possible problems are uncovered before you know of them. All required tools and equipment such as stamping dies, injection molding

#### **Key features**

- 40+ years of experience
- own Tool Shop
- fully vertical integration in manufacturing
- · exceptional flexibility
- · quick responsiveness
- · cost efficiency
- · excellent quality

### **Customized Connectors**

### Individually developed and produced



tools, assembling, inspection and packing equipment can be designed and made in ept's in-house tool shop. Hence, distances are short, response time is quick and, finally, reaction times on your requests are short. Furthermore, our in-house tool shop allows you to have functional prototypes available within 4 to 8 weeks after project kick-off.

#### **Highest Quality and Flexibility over Lifetime**

As in the development phase, ept is using an in-house approach during mass production of a program's life cycle. All production processes including stamping, reel-to-reel plating, molding, assembling, testing, and packaging are accomplished in-house and under ept's direct control. Hence, required changes to the product design and/or production process will be achieved quickly, smoothly, competent, and without disturbance of sub-suppliers. On top, and as ept is a family owned company with a flat hierarchy, you may escalate crucial requests easily even up to ept's owners.

With its more than 1.200 employees, ept operates manufacturing sites worldwide, such as in Germany, the Czech Republic, the USA, and China. Therefore, we can use the best suitable manufacturing location for your needs, such as local content requirements. Nevertheless and in any case, ept's passionate employees are dedicated to put quality and precision in first place of your valued project.

### ept - Your Partner

Share your applications or connector ideas with us. We are happy to analyze your concept and provide you with a feasibility study and an initial cost estimation.





# International presence - the ept locations

ept's roots are looked in the scenic landscape of southern Bavaria and from there ept has set out to become an international company. With production locations and sales offices in several countries as well as competent partners all over the world, ept is able to offer its connectors and solutions worldwide.

ept - your global partner



For your local contact please refer to www.ept.de











ept designs, produces and distributes electronic connectors for highquality applications. Founded by Bernhard Guglhör over 40 years ago, we are proud to remain an independent and family owned company. Today, we employ over 1.200 people at six locations worldwide.

Over decades we have built trusting and successful partnerships with our customers, who are the primary focus of all. Our products and core competencies are used in high-level applications.

With our motto "Precision with Passion" ept stands for the highest quality and reliability under the personal and individual touch of dedicated employees.

## We are looking forward to working with you. Your ept-Team

#### ept GmbH

Bergwerkstr. 50 86971 Peiting, Germany Tel. +49 (0) 88 61 / 25 01 0 Fax +49 (0) 88 61 / 55 07 sales@ept.de

#### ept, inc.

1624 Ashton Park Dr.
South Chesterfield, VA 23834, USA
Tel. +1 804 530 0820
800 323 2568
Fax +1 804 530 0837
sales@eptusa.com

### ept Electronic Precision Technology (Shanghai) Ltd.

6F Building 37, No. 333 Qin Jiang Road Shanghai, P. R. China Post code: 20 02 33

Tel. +86 (0) 21-54 26-09 88 Fax +86 (0) 21-64 95-39 49 sales@eptcn.com



www.ept.de